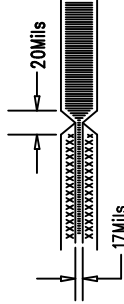


Linear Tech. Corp.
Demo Circuit 1132A

Top Side

| SIZE | QTY | SYM | PLATED | TOL |
|------|-----|-----|--------|--------|
| 187 | 4 | + | YES | +/-0.0 |
| 65 | 7 | X | YES | +/-0.0 |
| 10 | 76 | □ | YES | +/-0.0 |
| 70 | 2 | ◇ | NO | +/-0.0 |
| 95 | 8 | ⊗ | YES | +/-0.0 |
| 341 | 3 | ⊗ | YES | +/-0.0 |
| 35 | 2 | + | NO | +/-0.0 |
| 35 | 18 | + | YES | +/-0.0 |



9. DO NOT ALTER SOLDER MASK MAINTAIN .003" OVERSIZE ON SMT PADS. A .005" WEBBING IS REQUIRED BETWEEN SMD PADS.
10. PCB'S ARE TO BE ROHS COMPLIANT.

Fabrication Drawing

NOTES: UNLESS OTHERWISE SPECIFIED:

- ARTWORK P/N DEMO CIRCUIT 1132A
- FAB PER IPC-A-600. 4-Layers.
- MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4 .062 +/- .005 INCH THICKNESS WITH 2 OZ. COPPER FINISH ON TWO OUTER LAYERS AND 1 OZ. COPPER ON TWO INTERNAL LAYERS. FLAMMABILITY RATING: 94 V-2 MINIMUM .
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
- BOARD: SELECTIVE PLATED BOARD. SOLDER MASK OVER BARE COPPER, COLOR, GREEN LPI. GOLD IMMERSION (ENIG) BOTH SIDES. FOR SILKSCREEN: USE WHITE NON-CONDUCTIVE INK. PLATE THRU ALL HOLES WITH COPPER MIN. PLATING THICKNESS: 1 OZ. EXCEPT WHERE PLATING NOT REQUIRED
- DRILL: ALL HOLES SHALL BE DRILLED +/- .003 INCH WITH RESPECT TO CTR. OF DRILLED PAD. ALL HOLES FINISHED SIZE AFTER PLATING.
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO, DATE CODE OR ELECTRICAL TEST STAMP, BUT YOU MAY MODIFY PAD SIZE TO MEET END FINISH.
- SCORING FOR PANELIZED PCB: "PRODUCTION RUN ONLY"

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON ANGLE ± 1
2 PLACE ±.01 3 PLACE ±.005
INTERPRET DIM AND TOL
PER ASME Y14.5M - 1994

APPROVALS

| DRAWN | INIT | DATE |
|--------|-------------|---------|
| CHECK | | |
| DESIGN | L. Jensen | 2/12/08 |
| ENGR | G.Barbehenn | 2/12/08 |
| | | |
| | | |



TITLE: LTC3566EUF
High Efficiency USB Power Manager Plus 1A
Buck-Boost Converter

| SIZE | DEM | DC1132A | REV. |
|------|-----|---------|------|
| A | A | | A |

SCALE = NONE

SHEET 1 of 1